AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

- 1. (Currently amended) A method of metallizing a silicone rubber substrate, the method comprising the steps of:
- (i) depositing a primer layer of aluminum on a surface of a silicone rubber substrate, wherein the silicone rubber substrate has a coefficient of linear thermal expansion of at least 2×10^{-4} °C⁻¹, and
- (ii) depositing a layer of a ductile metal on the primer layer of aluminum, wherein the ductile metal is selected from gold, platinum, palladium, copper, silver, aluminum, and indium.
- 2. (Currently amended) The method according to claim 1, wherein the silicone rubber substrate is prepared by curing a curable silicone composition selected from a hydrosilylation-curable silicone composition, a peroxide curable silicone composition, a condensation-curable silicone composition, an epoxy-curable silicone composition[[;]], an ultraviolet radiation-curable silicone composition, and a high-energy radiation-curable silicone composition.

Claims 3-5 (Canceled)

- 6. (Currently amended) The method according to claim[[s]] 1, 2, 3, 4, or 5, wherein the ductile metal is gold or platinum.
- 7. (New) The method according to claim 2, wherein the curable silicone composition is a hydrosilylation-curable silicone composition comprising (i) an organopolysiloxane containing an average of at least two silicon-bonded alkenyl groups per molecule, (ii) an organohydrogensiloxane containing an average of at least two silicon-bonded hydrogen atoms per molecule in an amount sufficient to cure the composition, and (iii) a hydrosilylation catalyst.

- 8. (New) The method according to claim 2, wherein the curable silicone composition is a condensation-curable silicone composition comprising (i) an organopolysiloxane containing an average of at least two hydroxy groups per molecule, and (ii) a tri- or tetra-functional silane containing hydrolysable Si-O or Si-N bonds.
- 9. (New) The method according to claim 8, wherein the silane contains silicon-bonded alkoxy groups.
- 10. (New) The method according to claim 8, wherein the condensation-curable silicone composition further comprises a condensation catalyst.
- 11. (New) The method according to claim 2, wherein the curable silicone composition is a peroxide-curable silicone composition comprising an organopolysiloxane and an organic peroxide.
- 12. (New) The method according to claim 2, wherein the curable silicone composition further comprises an inorganic filler.
- 13. (New) The method according to claim 1, wherein the primer layer of aluminum has a thickness of from 1 to 200 nm.
- 14. (New) The method according to claim 13, wherein the primer layer of aluminum has a thickness of from 1 to 35 nm.
- 15. (New) The method according to claim 1, wherein the layer of a ductile metal has a thickness of from 20 to 500 nm.
- 16. (New) The method according to claim 15, wherein the layer of a ductile metal has a thickness of from 50 to 500 nm.